

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

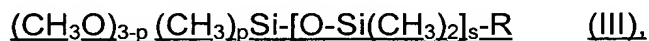
1. (Currently amended) A mold-release composition agent for the production of thermoset moldings with a hydrophobicized surface, ~~wherein this comprises~~ comprising:

(i) at least one polydimethylsiloxane with mold-release action of the general formula (I):



where m is 0 or an integer from 1 to 1000; and also

(ii) at least one reactive, optionally ~~where appropriate~~ hydrolyzable, silane compound, which is capable of reacting chemically *in situ* with the thermoset surface which forms during the molding process, the and the proportion of reactive silane compound corresponding to the general formula (III): of component (ii) is in the range from 5 per thousand (by weight) to 5% by weight, based on the total weight of components (i) and (ii)



where:

p is 0, 1, 2 or 3,

s is 0 or an integer from 1 to 100,

R is a monovalent, unsubstituted or hydroxyl-substituted, organic radical, which

includes at least one reactive group capable of reacting chemically with an epoxy

resin, and the proportion of the reactive silane of component (ii) is in the range from

5 per thousand by weight to 5% by weight based on the total weight of components

(i) and (ii).

2. (Currently amended) The mold-release composition agent as claimed in claim 1, wherein the proportion of the reactive silane compound of component (ii) is from 0.1% by weight to 2% by weight, based on the total weight of components (i) and (ii).

3. (Currently amended) The mold-release composition agent as claimed in claim 1, ~~wherein this~~ which comprises (iii) further ~~other~~ additives where appropriate, ~~preferably aqueous and/or non-aqueous solvents.~~

4. (Currently amended) ~~The mold-release agent as claimed in claim 1, wherein this comprises, as compound with mold-release action, a polydimethylsiloxane of the general formula (I),~~



~~where~~

~~m is zero or an integer from 1 to 1 000, preferably an integer from 10 to 50.~~

A mold-release composition for the production of thermoset moldings with a hydrophobicized surface, comprising:

(i) at least one polydimethylsiloxane with mold-release action of the general formula (I):



where m is 0 or an integer from 1 to 1000; and

(ii) at least one reactive, optionally hydrolyzable, silane compound which is capable of reacting chemically *in situ* with the thermoset surface which forms during the molding process, wherein the proportion of the reactive silane compound of component (ii) is in the range from 5 per thousand by weight to 5% by weight, based on the total weight of components (i) and (ii).

5-9. (Canceled)

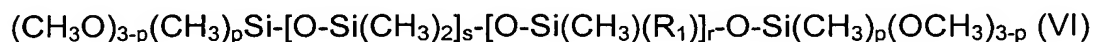
10. (Currently amended) ~~The mold-release agent as claimed in claim 1, wherein this comprises, as reactive silane compound, acetoxy-methyltrimethoxysilane, acetoxypropyltrimethoxy-silane, hydroxymethyltriethoxysilane, hydroxy-methyltrimethylsilane, and/or isocyanatopropyl-triethoxysilane.~~

A mold-release composition for the production of thermoset moldings with a hydrophobicized surface, comprising:

(i) at least one polydimethylsiloxane with mold-release action; and
(ii) at least one reactive, optionally hydrolyzable, silane compound which is capable of reacting chemically *in situ* with the thermoset surface which forms during the molding process, the proportion of the reactive silane compound of component (ii) is in the range from 5 per thousand by weight to 5% by weight, based on the total weight of components (i) and (ii);

wherein the reactive silane compound is at least one of acetoxy-methyltrimethoxysilane, acetoxypropyltrimethoxy-silane, hydroxymethyltriethoxysilane, hydroxy-methyltrimethylsilane, and isocyanatopropyl-triethoxysilane.

11. (Currently amended) The mold-release agent composition as claimed in claim 6 1, ~~wherein this~~ which comprises, as the at least one reactive silane compound of component (ii), a compound of the general formula (VI):



where in the compound of the formula (VI):

r is an integer from 1 to 5, ~~preferably 1, 2, or 3,~~

R₁, independently of one another, are as defined for R as claimed in claim 6 1, and

s is ~~as defined in claim 6~~ 0 or 1 to 10,

where the radicals -O-Si(CH₃)₂- and -O-Si(CH₃)(R₁) in the molecule have been arranged in any desired sequence; and

where in the compound of the formula (III), p is 0 or 1 and s is 0 or 1 to 10.

12. (Currently amended) The mold-release agent composition as claimed in claim 1, ~~wherein this~~ which is an oil-in-water emulsion.

13. (Currently amended) ~~The use of the mold-release agent~~ A method of producing a thermoset molding with a hydrophobicized surface, which comprises applying the mold-release composition as claimed in claim 1 ~~for the production of thermoset moldings with a hydrophobicized surface~~ to a mold wall.

14. (Currently amended) The use method as claimed in claim 13, which comprises ~~for comprising~~ producing moldings the thermoset molding from thermoset molding compositions, ~~preferably from polycondensates or polyadducts, which,~~ where appropriate, which optionally comprise conventional additives known per se.

15. (Currently amended) The use method as claimed in claim 14, wherein the thermoset molding ~~compositions are~~ is produced from a thermoset molding composition selected from the group consisting of curable phenol-formaldehyde plastics, curable bisphenol resins, curable urea-formaldehyde plastics, polyimides, polybenzimidazoles, epoxy resins, unsaturated polyester resins, ~~DAP~~ polydiallylphthalate resins, curable melamine-phenol-formaldehyde molding compositions, ~~or and~~ crosslinked polyurethanes, preferably aromatic and/or cycloaliphatic epoxy resins, or else PU casting compositions.

16. (Currently amended) The use method as claimed in claim 13, which comprises for the production of moldings using, as is known in the electrical industry, producing the thermoset molding using filled epoxy resins or PU resins.

17. (Canceled)

18. (Currently Amended) ~~The moldings produced as claimed in claim 17~~ A thermoset molding with a hydrophobicized surface produced by the method according to claim 13.

19-20. (Cancelled)

21. (New) The mold-release composition as claimed in claim 3, wherein component (iii) comprises an aqueous solvent and/or a non-aqueous solvent.

22. (New) The mold-release composition as claimed in claim 4, wherein m is an integer from 10 to 50.

23. (New) The mold-release composition as claimed in 11, wherein r is 1, 2 or 3.

24. (New) The method as claimed in claim 15, wherein the thermoset molding compositions are (a) aromatic epoxy resin and/or cycloaliphatic epoxy resins, or (b) PU casting compositions.

25. (New) The mold-release composition as claimed in claim 1, which further comprises, as a compound with mold-release action, at least one silane of the general formula (II),



where in the compound of the formula (II):

m is 0 or an integer from 1 to 1000,

n is an integer from 1 to 50, and

the dimethylsilyloxy groups and the methylhydrosilyloxy groups in the molecule are arranged in any desired sequence, and where the at least one silane compound of the formula (II) is present in a concentration of from 0.1% by weight to 50.0% by weight, based on the weight of the compounds in the formula (I).

26. (New) The mold-release composition as claimed in claim 25, wherein the at least one silane compound of the formula (II) is present in a concentration of

from 1.5% by weight to 5.0% by weight, based on the weight of the compounds in the formula (I), and n is an integer from 1 to 10 in the formula (II).

27. (New) The mold-release composition as claimed in claim 1, wherein m is an integer from 10 to 50 in the compound of the formula (I).

28. (New) The mold-release composition as claimed in claim 1, wherein p is 0 or 1, and s is 0 or 1 to 10 in the compound of the formula (III).

29. (New) The mold-release composition as claimed in claim 28, wherein the reactive substituent R is at least one of hydroxyl, amino, the isocyanate group, an ester group, and glycidyl in the compound of the formula (III).

30. (New) The mold-release composition as claimed in claim 29, wherein the ester group is an acetyl ester group, and the glycidyl is a 3-glycidoxypropyl residue.